DTIS 2019
Design & Technology of Integrated Systems in Nanoscale Era

16 – 18 April 2019, Mykonos, Greece

14th IEEE International Conference on Design & Technology of Integrated Systems in Nanoscale Era

Call for Papers

Aim of the Conference: to cope with the rapidly progressing technology which, today, reaches the nanometer scale. The areas of interest include the design, test and technology of electronic products, ranging from integrated circuit modules and printed circuit boards to full systems and microsystems, as well as the methodologies and tools used in the design, verification and validation of such products. Topics of the conference include, but are not limited to:

Integrated Systems Design:
- SOC, SIP design
- Multiprocessor systems
- Embedded systems
- Wireless systems
- Network on Chip
- Analog, Mixed Signal and RF systems
- MEMS and MOEMS systems
- Low Voltage and Low Power systems
- Innovative technologies
- Synthesis (physical, logic)
- Simulation, Validation and Verification
- 3D integration
- Hardware Security

Integrated Systems Technology:
- Nanoelecronics
- Device Modeling
- Material Characterization
- Failure Analysis
- New Components
- Packaging
- Process Technology
- Reliability Issues
- 3D Integration

Integrated Systems Testing:
- Defect and Fault Modeling
- Analog and Mixed Signal Testing
- MEMS/MOEMS Testing
- SOC and SIP Testing
- Delay Testing
- Memory Testing
- Fault Simulation, ATPG
- DFT, BIST, BISR
- On-line Testing
- Fault Tolerant Systems
- ATE Issues
- Alternative Test Strategies
- 3D Testing
- Test and Security Issues

Paper Submission: Authors are invited to submit original, unpublished research work to DTIS'19. Paper submissions should be complete manuscripts. The paper must clearly indicate the research area, main results and contributions. The manuscript should follow the instructions included in the author's kit on the conference website. Submitted articles should be in PDF format and uploaded on the on-line submission system. Submissions will be considered as evidence that, upon acceptance, the corresponding author assumes responsibility of preparing the final version in due time and the commitment of registration and presentation of the paper at the conference. Accepted papers will be considered for submission to IEEE Xplore*.

Special Issue on Elsevier Journal of Microelectronics Reliability: After the conference, authors are invited to submit extended paper versions to Journal of MR.
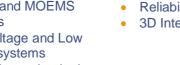
Proposals for Special Sessions: Proposals for original, high-quality Special Sessions addressing innovative research, highlighting significant topics and emerging issues, related to the conference theme, are welcome. Special session proposals should not exceed two pages, should describe the topic and intended audience, and a short bio of organizer(s). All special session proposals should be sent to the program chair.

Questions about the conference can be addressed to:

General Chair:
Ioannis Voyiatzis
voyageri@uniwa.gr

General Chair:
Michel Renovell
michel.renovell@lirmm.fr

Program Chair:
Elena-Ioana Vatajelu
Ioana.vatajelu@univ-grenoble-alpes.fr

General Chairs:

Ioannis Voyiatzis
UniWA, Greece
Michel Renovell
LIRMM, France

Program Chair:

Elena-Ioana Vatajelu
TIMA, France

Program Vice-Chair:

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Steering Committee:

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Key Dates:

Paper Submission:
January 25, 2019

Notification:
February 22, 2019

Camera Ready:
March 15, 2019

http://dtis2019.uniwa.gr/

* CEDA/IEEE sponsorship approval pending